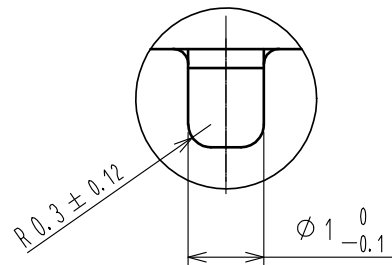


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本製品を車載用途などの高い信頼性が求められる機器にご使用の場合は、弊社までお問合せ下さい。

ELV, RoHS適合品

ELV, RoHS COMPLIANT

拡大図B(10:1)



Note1. The soldering process is allowed up to twice under the same condition. However, the interval between the first and second process must be maintained at the room temperature.

1. リフロー回数: 2回。但し、2回目のリフローにおいては、一度、室温に戻すこと。

Note2. The temperature indicates the board surface temperature on the connector lead area.

2. リフロー温度の測定は、コネクタリード部の基板表面温度を測定のこと。

Note3. Hand soldering: 280~300℃, 2s max.

3. 手半田温度: 280~300℃, 2S以内

Note4. Coplanarity: 0.1 max.

4. 端子平坦度: 0.1以下

Note5. Recommended thickness of PCB: 1.2mm

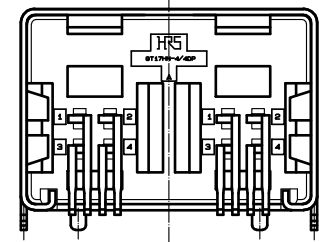
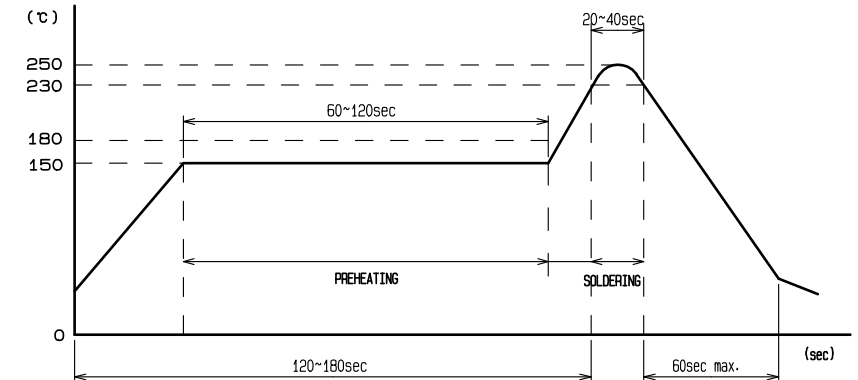
5. 推奨基板厚: 1.2mm

Note6. For the prevention excessive stress to connector and PCB, we recommend additional support mechanism if the flange was eliminated.

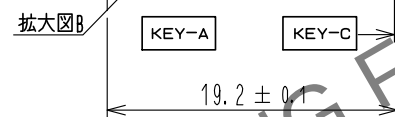
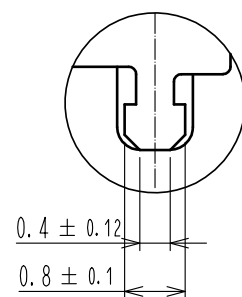
6. コネクタと基板間のこじり荷重を回避するために、フランジなしの本製品は、基板固定の機械的補強を設計的に配慮願います

RECOMMENDED REFLOW PROFILE

IR reflow condition	IR リフロー条件
Preheating area 150℃ for 60 to 120 seconds	予備加熱: 60~120秒, 150℃
Peak Temperature: 250℃	ピーク温度: 250℃
Soldering area 235±5℃ for 10 seconds max.	リフロー温度: 230~240℃, 10秒以内
230℃ min. for 10 to 30 seconds	230℃以上: 10~30秒



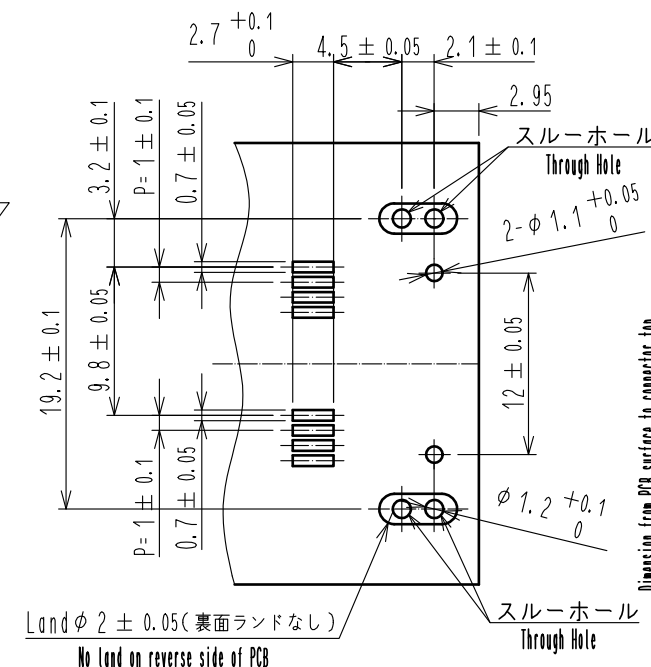
拡大図C(10:1)



実装状態図

IN COMBINATION WITH RIGHT-ANGLE CONNECTOR

GT17HN-4DS-HU



基板推奨寸法図
RECOMMENDED PCB LAYOUT

パネル寸法図
RECOMMENDED PANNEL LAYOUT

3	BRASS	TIN PLATING	6	PET	COVER TAPE
2	PPS	LIGHT GRAY	5	PS	EMBOSSED CARRIER TAPE
1	COPPER ALLOY	TIN PLATING	4	BRASS	TIN PLATING
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
UNITS mm		SCALE 2 : 1	COUNT 	DESCRIPTION OF REVISIONS	DESIGNED
HRS HIROSE ELECTRIC CO., LTD.		APPROVED : KI. HIROKAWA 20200326	DRAWING NO. ADC-366863-57-00		
		CHECKED : E.J. WAKATSUKI 20200325	PART NO. GT17HN-4/4DP-2H(CAC)(57)		
		DESIGNED : TS. KUBOTA 20200325	CODE NO. CL767-0015-0-57		
		DRAWN : YK. MITSUISHI 20200309			

